

PART NUMBER

26S10^BFA

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All re-creations are done with the approval of the Original Component Manufacturer. (OCM)

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceeds the OCM data sheet.

Quality Overview

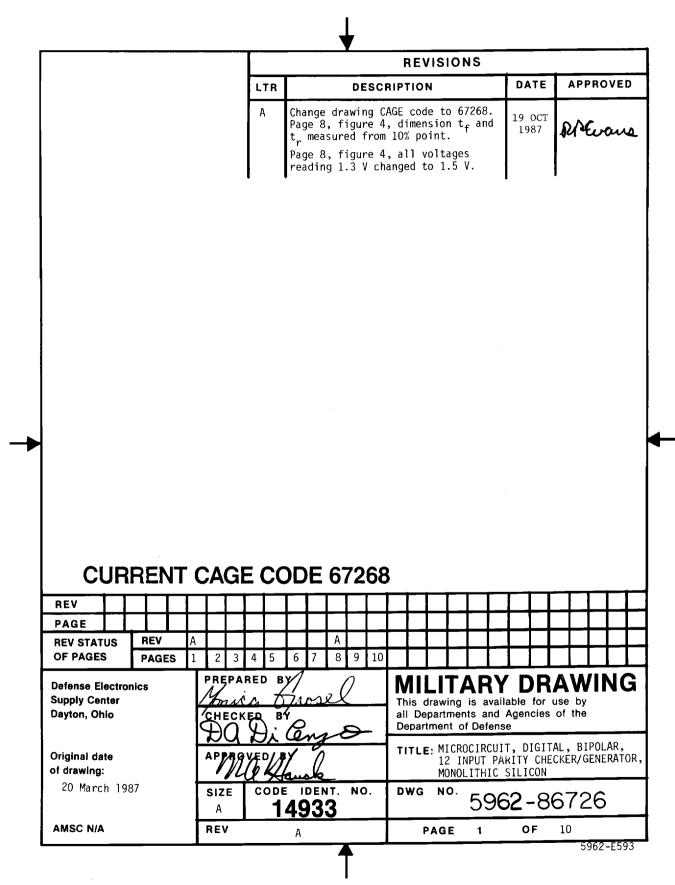
- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-38535
 - Class Q Military
 - Class V Space Level

Qualified Suppliers List of Distributors (QSLD)

• Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OCM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.



DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

1. SCOPE 1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices". 1.2 Part number. The complete part number shall be as shown in the following example: 5962-86726 01 Case outline Lead finish per Drawing number Device type (1.2.1)(1.2.2)MIL-M-38510 1.2.1 Device type. The device type shall identify the circuit function as follows: Generic number Device type Circuit function 01 93\$48 12 input parity checker/generator 1.2.2 <u>Case outlines</u>. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows: Outline letter Case outline Ε D-2 (16-lead, $1/4" \times 7/8"$) dual-in-line package F F-5 (16-lead, $1/4" \times 3/8"$) flat package 1.3 Absolute maximum ratings. -0.5 V to +7.0 V dc -1.5 V to +7.0 V dc Storage temperature range -------65°C to +150°C .99 W 1/ +300 C Lead temperature (soldering, 10 seconds) - - - - - Thermal resistance, junction-to-case (θ_{JC}): 25°C/W 20°C/W +150°C -30 mA to 5.0 mA DC output current into output ------+30 mA 1.4 Recommended operating conditions. +4.5 V to 5.5 V dc maximum 2.0 V dc 0.8 V dc Ambient operating temperature range $(T_A) - - - - -$ -55°C to +125°C 1/ Must withstand the added P_D due to short circuit test (e.g., I_{OS}). SIZE DWG NO MILITARY DRAWING A 5962-86726 **DEFENSE ELECTRONICS SUPPLY CENTER** DAYTON, OHIO REV PAGE 2 DESC FORM 193A **FEB 86**

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification and standard</u>. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawiny to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510

- Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth table. The truth table shall be as specified on figure 2.

3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.2.5 Switching waveforms. The switching waveforms shall be as specified on figure 4.

3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended ambient operating temperature range.

3.4 <u>Marking</u>. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.

3.5 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.6 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

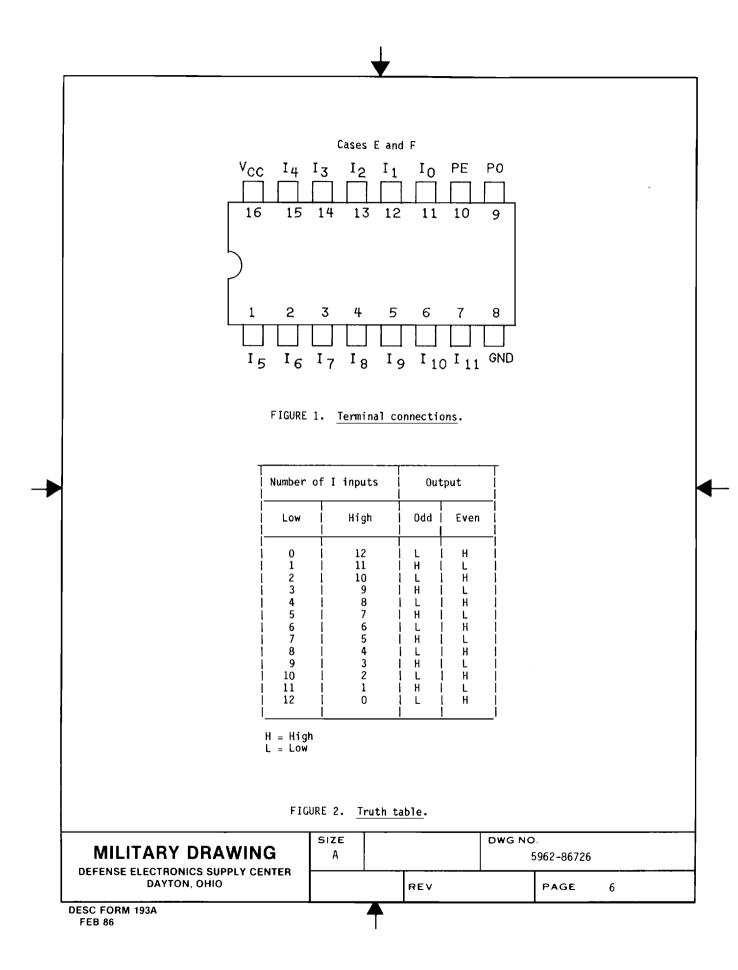
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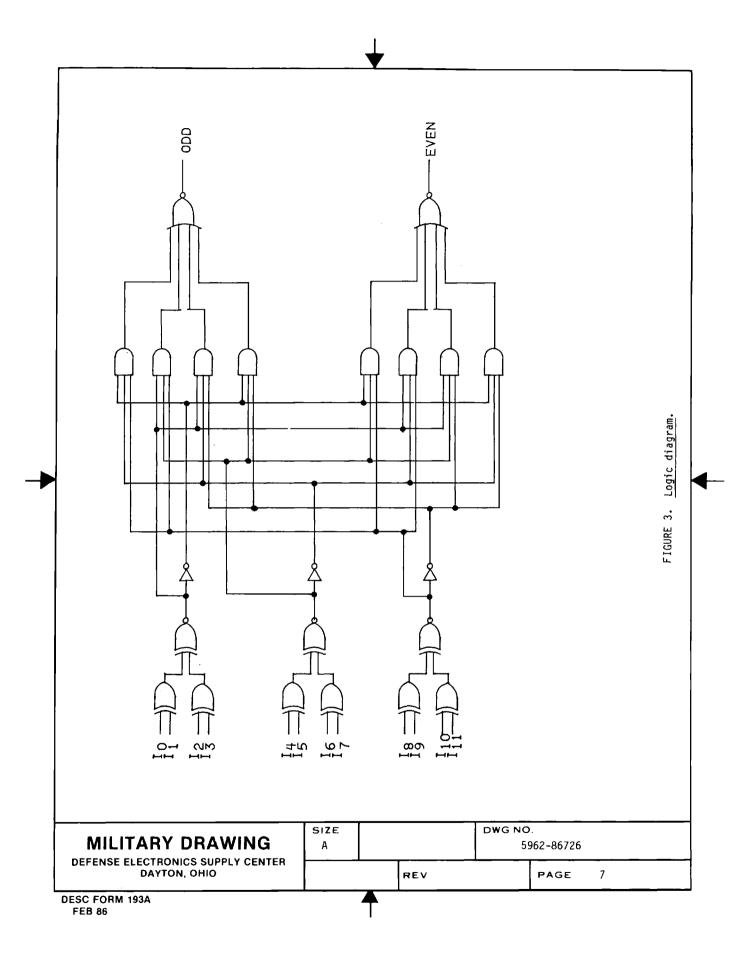
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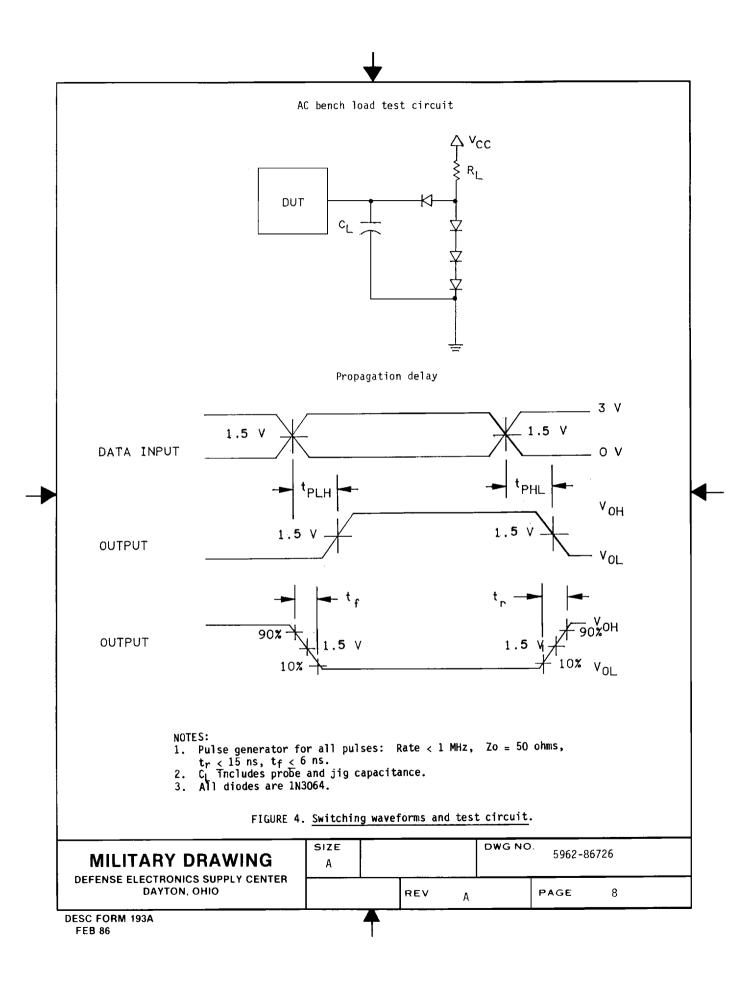
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Test	1						
	Symbol 	 Condi -55°C <u>≺</u> T _A	tions < +125°C	Group A subgroups		mits Max	Un
High level output voltage	V _{OH}	V _{CC} = +4.5 V V _{IN} = 2.0 V or I _{OH} = -1 mA	0.8 V	1,2,3	2.5		1
Low level output voltage	VOL	$V_{CC} = +4.5 V$ $V_{IN} = 2.0 V or$ $I_{OL} = 20 mA$	0.8 V	1,2,3		0.50	V
Input clamp voltage	VIC	V _{CC} = +4.5 V I _{IN} = -18 mA		1,2,3		-1.2	۷
High level input current	I I I H1	$V_{CC} = +5.5 V$ $V_{IN} = 2.7 V$		1,2,3		20	μ
		V _{CC} = +5.5 V V _{IN} = 5.5 V		1,2,3		1.0	17
Low level input current	IIL	$V_{CC} = +5.5 V$ $V_{IN} = 0.5 V$		1,2,3		-0.8	m
Output short circuit current	I I _{OS}	V _{CC} = +5.5 V V _{OUT} = 0 V	<u>1</u> /	1,2,3	- 40	- 100	រា
Supply current	I ^I CC	l 00	oth outputs pen. All inputs 4.5 V	1,2,3		80	ព
Functional testing		See 4.3.1c		7,8			
Propagation delay from IO through Ill to even output	t _{PLH1}	$C_{L} = 15 \text{ pF}$ $R_{L} = 280\Omega$ (See figure 4)	<u>2</u> /	9		28	n
		T 	3/	9,10,11		35	n
	t _{PHL 1}		2/	9		28	n
			<u>3</u> /	9,10,11		35 35	n
See footnotes at end of table.							
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Test		Cond	 Group A Limits		 Unit		
		55°C <u><</u> T	A <u><</u> +125°C	subgroups	Min	Max	Ţ Ţ
Propagation delay from IO through Iil to odd output	t _{PLH2}	 C _L = 15 pF R _L = 280Ω (See figure 4) 	<u>2</u> /	9		28	ns
			3/	9,10,11		35	ns
	tphl 2	T 	2/	9		28	ns
		 	3/	9,10,11		35	ns
$\frac{1}{2}$ Not more than one output condition should not exce	should be ed 1 seco	shorted at a ti nd.	me and the du	ration of the s	hort ci	rcuit	
$\frac{2}{V_{CC}} = 5.0 \text{ V}.$							
$3/V_{CC} = 4.5 V$ to 5.5 V.							
3.7 Notification of change. IL-STD-883 (see 3.1 herein).	Notific	ation of change	to DESC-ECS s	hall be require	ed in ac	cordanc	ce with
3.8 <u>Verification and review</u> eview the manufacturer's faci e made available onshore at t	lity and	DESC's agent, an applicable requi	d the acquiri	ng activity ref	tain the	option	n to
	ne option	of the reviewer	•		e docume	incación	n shall
4. QUALITY ASSURANCE PROVIS		of the reviewer	•		e uocane	incaci or	n shall
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 4. QUALITY ASSURANCE PROVIS 4.1 Sampling and inspection of MIL-M-38510 to the extent 4.2 Screening. Screening s onducted on all devices prior hall apply: a. Burn-in test (method 1 (1) Test condition C o 3.5 herein). (2) T_A = +125°C, minim b. Interim and final elec interim electrical par 	IONS . Sampli specifie hall be i to quali 015 of MI r D using um. trical te ameter te pection.	of the reviewer ing and inspectio d in MIL-STD-883 in accordance wit ty conformance i L-STD-883). the circuit sub est parameters sh ests prior to bur Quality conform	n procedures (see 3.1 here h method 5004 nspection. The mitted with t hall be as spe n-in are optimance inspecti	shall be in acc ein). of MIL-STD-88 he following ac he certificate cified in table onal at the dis on shall be in ns. The follow	cordance 3, and s iditiona of comp e II her scretion accorda	e with s shall bu l crite pliance rein, e. a of the ance wi	section e eria (see xcept e th
4. QUALITY ASSURANCE PROVIS 4.1 Sampling and inspection of MIL-M-38510 to the extent 4.2 Screening. Screening s onducted on all devices prior hall apply: a. Burn-in test (method 1 (1) Test condition C o 3.5 herein). (2) $T_A = +125^{\circ}C$, minim b. Interim and final elec interim electrical par manufacturer. 4.3 Quality conformance ins ethod 5005 of MIL-STD-883 inc	IONS Sampli specifie hall be i to quali 015 of MI r D using um. trical te ameter te pection. Tuding gr	of the reviewer ing and inspectio d in MIL-STD-883 in accordance wit ty conformance i L-STD-883). the circuit sub est parameters sh ests prior to bur Quality conform	n procedures (see 3.1 here h method 5004 nspection. The mitted with t hall be as spe n-in are optimance inspecti	shall be in acc ein). of MIL-STD-88 he following ac he certificate cified in table onal at the dis on shall be in	ordance 3, and s iditiona of comp e II her scretion accorda wing add	e with s shall bu l crite pliance rein, e. a of the ance wi	section e eria (see xcept e th







4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroups 7 and 8 tests shall verify the truth table.
- 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - (1) Test condition C or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004) 	
IFinal electrical test parameters (method 5004) 	1*,2,3,7,8,9, 10,11
Group A test requirements (method 5005)	1,2,3,7,8,9, 10**,11**
Groups C and D end-point electrical parameters (method 5005)	1,2,3

TABLE II. Electrical test requirements.

* PDA applies to subgroup 1.

** Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

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5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

6.4 <u>Approved source of supply</u>. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

 Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1</u> /
5962-8672601EX	34335	AM93S48/BEA
5962-8672601FX	34335	AM93S48/BFA

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

34335

Vendor name and address

Advanced Micro Devices, Incorporated 901 Thompson Place P.O. Box 3453 Sunnyvale, CA 94088

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